

GOLD ON ALUMINUM NITRIDE

Thick film gold on aluminum nitride provides excellent wire bond adhesion, electrical conductivity and leach resistance.

Typical Properties of Gold Metallization System		
Resistivity		6.0 mΩ/sq
Printing Resolution	(line/space)	125 μm/125 μm
Wettability	(5 sec dip, 50 In/50 Pb solder)	95 – 100%
Wire Bond Adhesion		
Initial	(Au wire, 4.0 mil dia) @125°C	68 g
Aged 24 h at 300°C	(Au wire, 4.0 mil dia)	58 g
Adhesion*		≥68.9 MPa

*Pull testing with 3.0 mm square pads and epoxy adhesive aluminum studs.

Sienna's technical team is ready to help you implement Aluminum Nitride in your next generation of products.

Contact us for applications assistance and fast prototyping.

The information given herein is believed to be reliable but Sienna Technologies, Inc. makes no expressed or implied warranties as to the accuracy of the information. Sienna Technologies, Inc. assumes no liability arising out of the use of this information by others.

425-485-7272

www.siennatech.com

11611 49th Place West
Mukilteo, WA 98275

